



Revision: 1.0
Date: 2-Feb-05

Statement of Materials, Construction

8L COB -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Substrate	BT Resin	0.01049	BT Epoxy	Proprietary	0.00262	15.27373	25
				Glass Crossing	Proprietary	0.00419	24.37688	39.9
				Cu	7440-50-8	0.00367	21.38323	35
				Ni	7440-02-0	0.00001	0.06109	0.1
2	Die	Silicon Chip	0.001106	Si	7440-21-3	0.00111	6.44147	100
				Epoxy resin (5-25)	Proprietary	0.00004	0.24898	15
3	Die attach material	84-1 LMISR4	0.000285	Silver (70-85)	7440-21-3	0.00023	1.32790	80
				Aromatic Amine (1-10)	Proprietary	0.00001	0.08299	5
				Au	7440-57-5	0.00037	2.17800	99.99
5	Encapsulation NT-309HQ	Epoxy Resin	0.004915	Bisphenol A type	25068-38-6	0.00265	15.45778	54
				Epoxy resin	2451-62-9	0.00079	4.58008	16
				Tetra Hydrophthalic Anhydride	85-43-8	0.001474	8.58737	29.999
				Halogenated Flame Retardants	Proprietary	0.00000	0.00029	0.001
Total Package weight			0.0172					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys